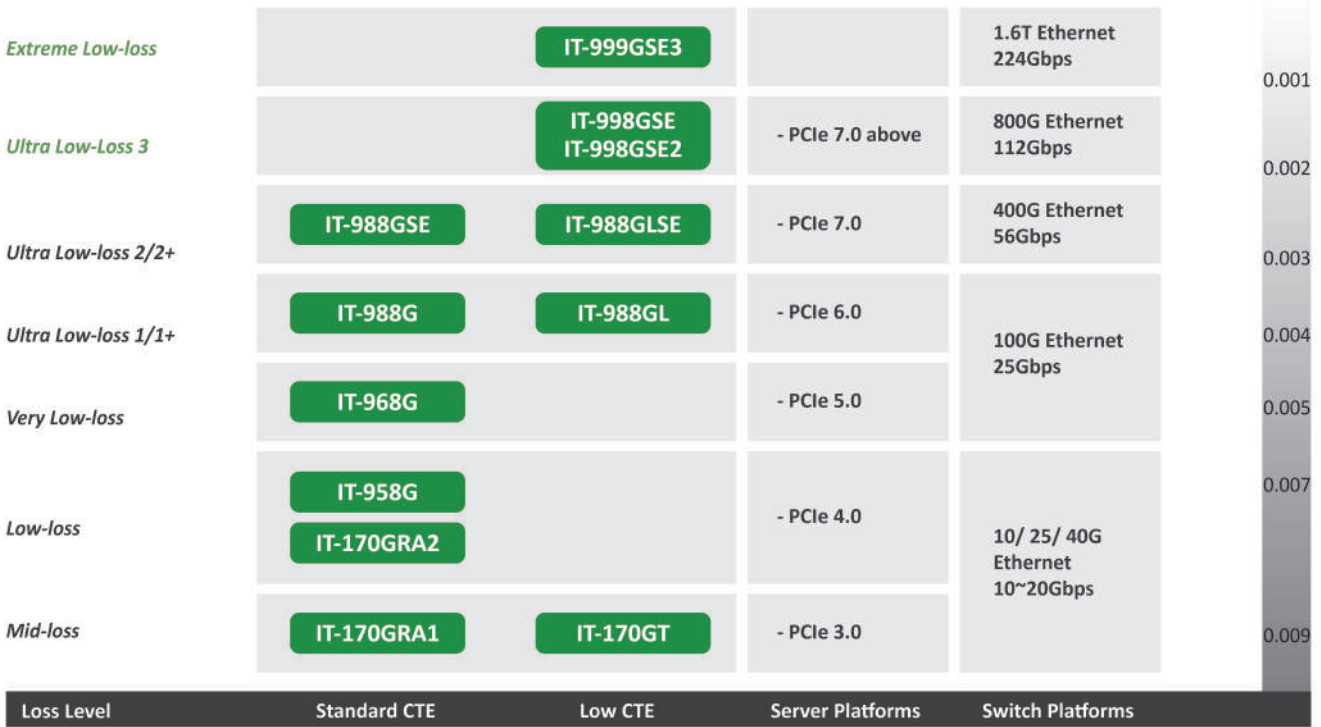


Test Item	Condition	Unit	IT-968G	IT-968GSE	IT-988G	IT-988GL	IT-988GSE	IT-988GLSE	IT-998GSE	IT-998GSE2	IT-999GSE3
Loss level			VLL	ULL	ULL	ULL	ULL	ULL	SULL	SULL	SULL
Glass Transition Temp (Tg)	TMA	°C	175	175	175	180	180	180	200 (DMA)	200 (DMA)	190 (DMA)
CTE	X/Y-axis	α1	ppm/°C	12/14	12/14	12/14	13/13	16/17	11/11	12/13	12/13
	Z-axis	α1 / α2	ppm/°C	45 / 260	45 / 260	50/270	35/190	53/280	35/185	45/225	45/225
		50 - 260°C	%	2.3	2.3	2.5	1.7	2.7	1.7	2.0	2.0
Td (5% wt loss)	TGA	°C	400	400	400	400	400	380	380	400	
Thermal Resistance	T288	min	> 60	> 60	> 60	> 60	> 60	> 60	> 60	> 60	
Peeling Strength	1oz (Low Profile)	lb/in	3.5	3.2	4.0	3.5	4.1	3.5	3.0	3.0	
Dielectric Constant	10 GHz	-	3.59	3.16	3.76	3.63	3.30	3.30	3.14	3.05	
Dielectric Factor	10 GHz	-	0.0050	0.0036	0.0035	0.0035	0.0026	0.0026	0.0013	0.0011	



Material Selection Guide for Server

PCIe Generation	PCIe 3.0	PCIe 4.0	PCIe 5.0	PCIe 6.0
Transmission Rate	8Gbps	16Gbps	32Gbps	64Gbps
Dominant Frequency	4GHz	8GHz	16GHz	16GHz
PCB Electrical Performance	0.65 dB/in	0.85 dB/in	0.96 dB/in	0.85 dB/in

Material	IT-170GRA1	IT-170GRA2 / IT-958G	IT-968G	IT-988GL
• Mid-Loss	• Very Low-Loss	• Ultra Low-Loss 1+	• Halogen Free	• Halogen Free
• Halogen Free	• Halogen Free	• Halogen Free	• CTE (Z-axis 50-260°C) 2.7%	• CTE (Z-axis 50-260°C) 2.7%
• CTE (Z-axis 50-260°C) 2.7%	• CTE (Z-axis 50-260°C) 2.4%	• CTE (Z-axis 50-260°C) 2.3%	• DK 3.72, Df 0.0089 @100Hz	• DK 3.63, Df 0.0041 @100Hz
• DK 3.72, Df 0.0089 @100Hz	• DK 3.70, Df 0.0075 @100Hz	• DK 3.59, Df 0.0050 @100Hz	• RTF Cu	• RTF4 Cu
• RTF Cu	• RTF2 Cu	• RTF2/RTF3 Cu		

Material Selection Guide for Switch

Gigabit Ethernet	100G	400G	800G	1.6T
Amplitude Modulation	NRZ	PAM4	PAM4	PAM4
Transmission Rate	28Gbps	56Gbps	112Gbps	224Gbps
Dominant Frequency	12.89GHz or 14GHz	13.28GHz or 14GHz	26.56GHz or 28GHz	53.12GHz or 56GHz

Material	IT-968G	IT-988GLSE	IT-998GSE2	IT-999GSE3
• Very Low-Loss	• Ultra Low-Loss 2	• Ultra Low-Loss 3	• Ultra Low-Loss 3	• Extreme Low-Loss
• Standard E-glass	• Low-Dk-glass	• Low-Dk 2-glass	• Low-Dk 2-glass	• G-glass
• DK 3.62, Df 0.0036 @100Hz	• DK 3.12, Df 0.0021 @100Hz	• DK 3.06, Df 0.0011 @100Hz	• DK 3.06, Df 0.0011 @100Hz	• Ck 2.95, Df 0.0007 @100Hz
• RTF4/RTF5 Cu	• RTF4/RTF5 Cu	• Low-Df RTF4 Cu	• Low-Df RTF4 Cu	• Above RTF4 Cu
• 20k Thermal Reliability	• 20k Thermal Reliability	• 20k Thermal Reliability	• 20k Thermal Reliability	• 20k Thermal Reliability
• Half-Size 288C 10x, 0.5mm Pitch	• Half-Size 288C 10x, 0.5mm Pitch	• Half-Size 288C 10x, 0.5mm Pitch	• Half-Size 288C 10x, 0.5mm Pitch	• Half-Size 288C 10x, 0.5mm Pitch
• Full-Size 288C 10x, 0.5mm Pitch	• Full-Size 288C 10x, 0.5mm Pitch	• Full-Size 288C 10x, 0.5mm Pitch	• Full-Size 288C 10x, 0.5mm Pitch	• Full-Size 288C 10x, 0.5mm Pitch
• 7x Multi-lamination (3x4-6)	• 7x Multi-lamination (3x4-6)	• 7x Multi-lamination (3x4-6)	• 7x Multi-lamination (3x4-6)	• 7x Multi-lamination (3x4-6)

HIGH DENSITY INTERCONNECTION (HDI)

Test Item		Condition	Unit	IT-170GT	IT-170GRA2	IT-170GL	IT-602G	IT-603G	
Thermal	Glass Transition Temperature (Tg)	DMA	°C	---	---	---	230	215	
		TMA		---	---	---	210	195	
		DSC		185	175	200	---	---	
	CTE	X/Y-axis	α_1	ppm/°C	13	13	13	10	9
		Z-axis	α_1 / α_2	ppm/°C	40/180	40/215	20/130	25/120	25/130
	Td (5% wt loss)	TGA	°C	380	390	390	415	400	
	Heat Resistance	T288	min	> 60	> 60	> 60	> 60	> 60	
Water Absorption		%	0.1	0.10	0.10	0.20	0.12		
Mechanical	Flexural Strength	Warp Fill	N/mm2	480-510 400-430	450-480 380-410	450-480 380-410	420-450 390-420	460-490 400-430	
	Peel Strength	1oz (RTF)	lb/in	4.0	5.0	5.0	5.0	4.0	
Electrical	Permittivity (Dk)	1 GHz	-	4.0	4.1	4.1	3.6	3.4	
		10 GHz	-	3.9	3.8	3.8	3.5	3.2	
	Loss Tangent (Df)	1 GHz	-	0.0085	0.0073	0.0073	0.0047	0.0024	
		10 GHz	-	0.0095	0.0081	0.0081	0.0061	0.0032	
Product Stage				HVM	HVM	HVM	Sample	R&D	

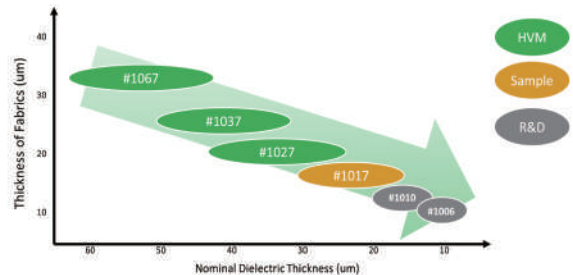
銅箔 COPPER FOIL

- Low roughness copper to minimize skin effect at high frequency.
- Improved peel strength. Good adhesion of copper foil to resin.
- Carrier Copper (EX 2/3 um, FL 1.5/3 um, GN 1.5 um) available.

Foil Type	Rolling side roughness (Ra)	CCP 厚度	Resin 厚度	Co-Foil 厚度	Metal (TOP) 厚度 (公制)	Through Hole 厚度 (mm)	Performance 特性	Fabric 說明
BT1	0.9 um	BT1-0	TLC-400	BT1-1	MLD-0			
BT2	2.0 um	BT1-20	HL	BT2-1	MLD-05			
BT3	0.1 um	BT1-35*	HLA	BT3-1	MLD-04			
BT4	0.1 um	BT1-45*		BT4-1	MLD-05*			
BT5	0.1 um	BT1-55*		BT5-1				
BT6	0.1 um	BT1-65*		BT6-1				
BT7	0.1 um	BT1-75*		BT7-1				
BT8	0.1 um	BT1-85*		BT8-1				
BT9	0.1 um	BT1-95*		BT9-1				
BT10	0.1 um	BT1-105*		BT10-1				
BT11	0.1 um	BT1-115*		BT11-1				
BT12	0.1 um	BT1-125*		BT12-1				
BT13	0.1 um	BT1-135*		BT13-1				
BT14	0.1 um	BT1-145*		BT14-1				
BT15	0.1 um	BT1-155*		BT15-1				
BT16	0.1 um	BT1-165*		BT16-1				
BT17	0.1 um	BT1-175*		BT17-1				
BT18	0.1 um	BT1-185*		BT18-1				
BT19	0.1 um	BT1-195*		BT19-1				
BT20	0.1 um	BT1-205*		BT20-1				
BT21	0.1 um	BT1-215*		BT21-1				
BT22	0.1 um	BT1-225*		BT22-1				
BT23	0.1 um	BT1-235*		BT23-1				
BT24	0.1 um	BT1-245*		BT24-1				
BT25	0.1 um	BT1-255*		BT25-1				
BT26	0.1 um	BT1-265*		BT26-1				
BT27	0.1 um	BT1-275*		BT27-1				
BT28	0.1 um	BT1-285*		BT28-1				
BT29	0.1 um	BT1-295*		BT29-1				
BT30	0.1 um	BT1-305*		BT30-1				
BT31	0.1 um	BT1-315*		BT31-1				
BT32	0.1 um	BT1-325*		BT32-1				
BT33	0.1 um	BT1-335*		BT33-1				
BT34	0.1 um	BT1-345*		BT34-1				
BT35	0.1 um	BT1-355*		BT35-1				
BT36	0.1 um	BT1-365*		BT36-1				
BT37	0.1 um	BT1-375*		BT37-1				
BT38	0.1 um	BT1-385*		BT38-1				
BT39	0.1 um	BT1-395*		BT39-1				
BT40	0.1 um	BT1-405*		BT40-1				
BT41	0.1 um	BT1-415*		BT41-1				
BT42	0.1 um	BT1-425*		BT42-1				
BT43	0.1 um	BT1-435*		BT43-1				
BT44	0.1 um	BT1-445*		BT44-1				
BT45	0.1 um	BT1-455*		BT45-1				
BT46	0.1 um	BT1-465*		BT46-1				
BT47	0.1 um	BT1-475*		BT47-1				
BT48	0.1 um	BT1-485*		BT48-1				
BT49	0.1 um	BT1-495*		BT49-1				
BT50	0.1 um	BT1-505*		BT50-1				
BT51	0.1 um	BT1-515*		BT51-1				
BT52	0.1 um	BT1-525*		BT52-1				
BT53	0.1 um	BT1-535*		BT53-1				
BT54	0.1 um	BT1-545*		BT54-1				
BT55	0.1 um	BT1-555*		BT55-1				
BT56	0.1 um	BT1-565*		BT56-1				
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BT58	0.1 um	BT1-585*		BT58-1				
BT59	0.1 um	BT1-595*		BT59-1				
BT60	0.1 um	BT1-605*		BT60-1				
BT61	0.1 um	BT1-615*		BT61-1				
BT62	0.1 um	BT1-625*		BT62-1				
BT63	0.1 um	BT1-635*		BT63-1				
BT64	0.1 um	BT1-645*		BT64-1				
BT65	0.1 um	BT1-655*		BT65-1				
BT66	0.1 um	BT1-665*		BT66-1				
BT67	0.1 um	BT1-675*		BT67-1				
BT68	0.1 um	BT1-685*		BT68-1				
BT69	0.1 um	BT1-695*		BT69-1				
BT70	0.1 um	BT1-705*		BT70-1				
BT71	0.1 um	BT1-715*		BT71-1				
BT72	0.1 um	BT1-725*		BT72-1				
BT73	0.1 um	BT1-735*		BT73-1				
BT74	0.1 um	BT1-745*		BT74-1				
BT75	0.1 um	BT1-755*		BT75-1				
BT76	0.1 um	BT1-765*		BT76-1				
BT77	0.1 um	BT1-775*		BT77-1				
BT78	0.1 um	BT1-785*		BT78-1				
BT79	0.1 um	BT1-795*		BT79-1				
BT80	0.1 um	BT1-805*		BT80-1				
BT81	0.1 um	BT1-815*		BT81-1				
BT82	0.1 um	BT1-825*		BT82-1				
BT83	0.1 um	BT1-835*		BT83-1				
BT84	0.1 um	BT1-845*		BT84-1				
BT85	0.1 um	BT1-855*		BT85-1				
BT86	0.1 um	BT1-865*		BT86-1				
BT87	0.1 um	BT1-875*		BT87-1				
BT88	0.1 um	BT1-885*		BT88-1				
BT89	0.1 um	BT1-895*		BT89-1				
BT90	0.1 um	BT1-905*		BT90-1				
BT91	0.1 um	BT1-915*		BT91-1				
BT92	0.1 um	BT1-925*		BT92-1				
BT93	0.1 um	BT1-935*		BT93-1				
BT94	0.1 um	BT1-945*		BT94-1				
BT95	0.1 um	BT1-955*		BT95-1				
BT96	0.1 um	BT1-965*		BT96-1				
BT97	0.1 um	BT1-975*		BT97-1				
BT98	0.1 um	BT1-985*		BT98-1				
BT99	0.1 um	BT1-995*		BT99-1				
BT100	0.1 um	BT1-1005*		BT100-1				

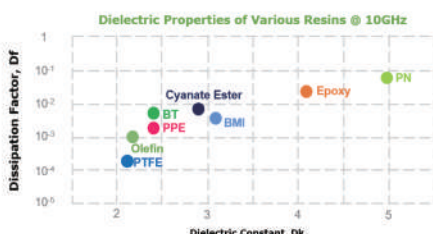
玻璃纖維布 GLASS FABRIC

- Ultra-thin glass fabric to meet required dielectric thickness.
- Low Dk (LDK/LDK2) and Q-Glass to realize Super-Ultra-Low-Loss.
- Glass-free (RCC) solution for next generation HDI/SLP design.



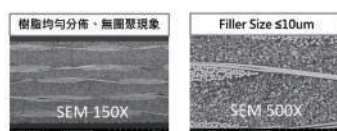
樹脂配方 RESIN MIXTURE

- Low Dk and Df.
- Improved thermal reliability.
- Low CTE. Good Dimensional Stability.



技術品質 ENGINEERING QUALITY

- Special fuse treatment and dispersion process to prevent from filler/resin aggregation. 100% auto-inspection by CCD.
- Clean Room management (class 1K) in critical production floors.



◆ Product Lineup for Automotive

Infotainment & Bended Display
IT-158, IT-180A, IT-170GT

Active safety & ADAS
IT-150DA, IT-968G
IT-170GT, IT-88GMW

V2X- 5G & 6G NAD
IT-170GT, IT-968G

HPC & Autonomous
IT-170GT, IT-968G, IT-988GL

HEV/EV/BMS
IT-170GT, IT-258GA3,
IT-858G

◆ Advanced Applications for Automotive

- Active Safety (ADAS, Radar and Antenna Module)

High Frequency & High Speed Material

IT-150DA, IT-968G, IT-170GT, IT-88GMW

- Internet Vehicle (5G & 6G Networking Access Device)

HDI and High Speed : IT-170GT, IT-968G

- HEV/EV/BMS

High Tg, Heavy Cu, and Low CTE:

IT-170GT, IT-258GA3, IT-180A, IT-858G

- Autonomous Driving (dGPU and HPC)

HDI and High Speed : IT-170GT, IT-170GRA2, IT-968G, IT-988GL

- Infotainment & Bended Display


HDI and Bendable : IT-158, IT-180A, IT-170GT



Characteristics		Unit	IT-258GA3	IT-170GT	IT-858G
Reliability	Applicable voltage	Volts	≤ 1,000		≤ 1,500
	Applicable copper thickness	ounce	≤ 2oz		≤ 12oz
	Anti-CAF Performance (min. hole wall - hole wall)	mm	0.8 @1,000V		0.8 @1,000V 1.1 @1,500V
Thermal	Glass Transition Temp. (Tg)	°C	155	185	200
	Td (5% wt loss)	°C	385	380	395
	Thermal Resistance (T288)	min	>60	>60	>60
	X/Y axis CTE (40-125°C)	ppm/°C	11-15	11-13	11-15
	Z-axis CTE (50-260°C)	%	2.8	1.7	1.4
	MOT	°C	130	150	150
Electrical	Permittivity (Dk ∙ 1GHz)	-	4.4	4.0	4.9
	Loss Tangent (Df ∙ 1GHz)	-	0.0140	0.0085	0.0120
	CTI	PLC	1	2	2

◆ **Advantages**

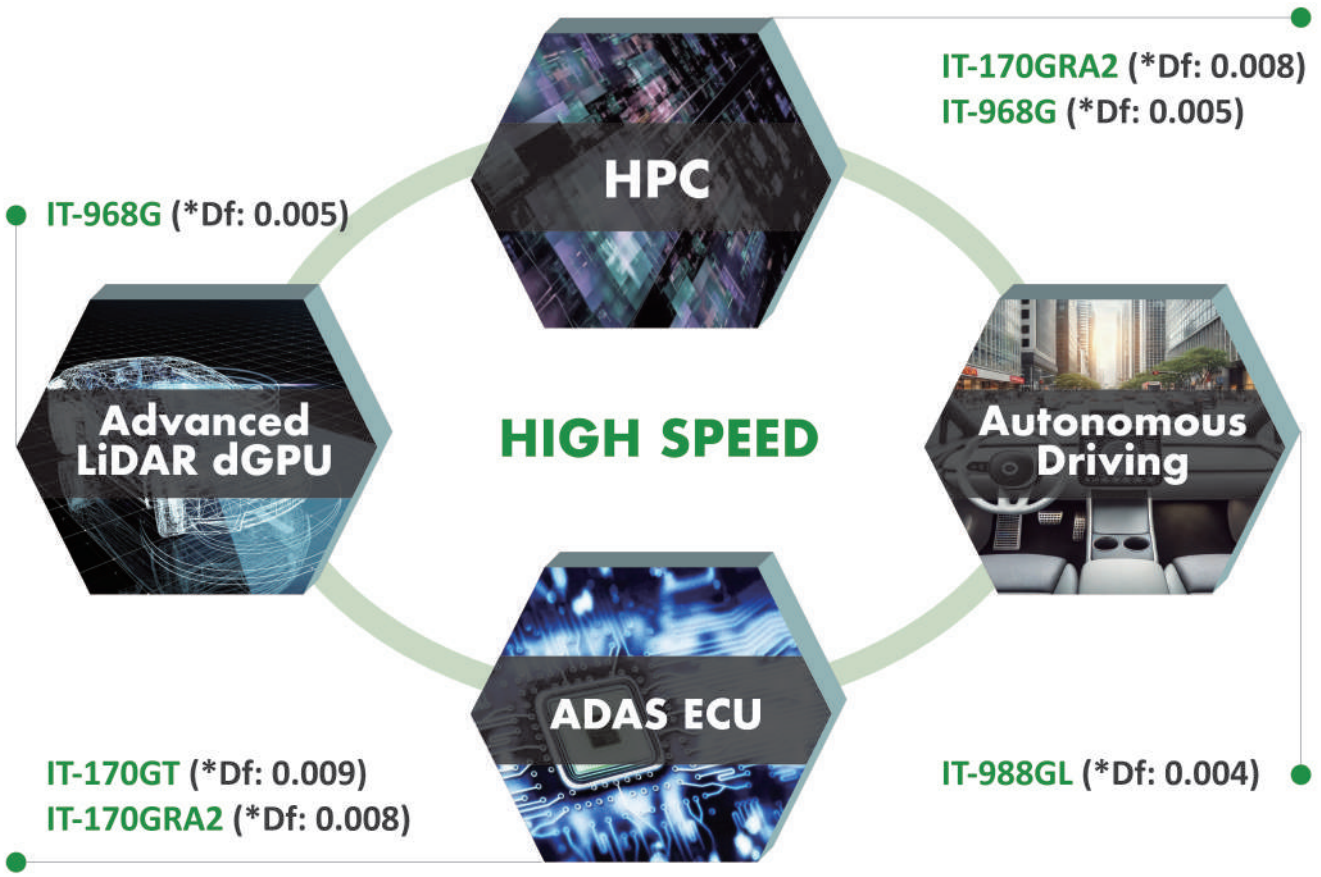
- High Tg and Low CTE
- Excellent Anti-CAF Performance (1,000V and 1,500V and above)
- High Voltage
- High Current
- Halogen Free



◆ **Applications**

- Heavy Copper Design (3, 6, 12oz)
- Electric Vehicle Material Solution
- Suitable for HDI Design

Autonomous Driving Solution

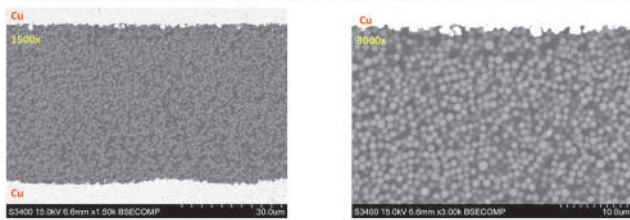


GLASS-FREE/ HIGH TG/ GOOD RELIABILITY

Test Item		Condition	Unit	IT-701G	IT-702G	IT-703G
Application				Advanced HDI/Substrate-Like PCB/Package Substrate		
Thermal	Glass Transition Temperature (Tg)	DMA	°C	175	240	239
		TMA		155	220	215
	CTECTE (Z-axis)	$\alpha1 / \alpha2$	ppm/°C	25/100	20/70	20/70
	Td (5% wt loss)	TGA	°C	390	392	395
	Heat Resistance	T300	min	>60	>60	>60
	Water Absorption	PCT 3Hr	%	<1.0	<0.3	<0.3
Mechanical	Young's Modulus	RT	GPa	7.5	1.5	1.3
	Tensile Strength	RT	Mpa	105	125	110
	Elongation	RT	%	2.2	1.5	1.3
	Peel Strength	Toz (RTF)	Kgf/cm	>0.5	>0.5	>0.5
Electrical	Permittivity (Dk)	1 GHz	-	3.3	3.2	3.2
		10 GHz	-	3.2	3.1	3.2
	Loss Tangent (Df)	1 GHz	-	0.0130	0.0023	0.0018
		10 GHz	-	0.0150	0.0026	0.0020
Product Stage				Sample	Sample	R&D

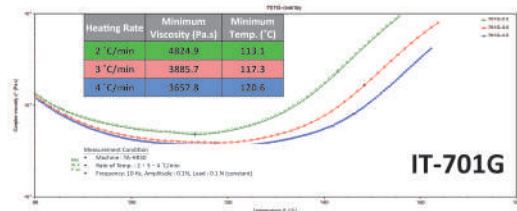
技術品質 ENGINEERING QUALITY

- Special fuse treatment and dispersion process to prevent from filler/resin aggregation. 100% auto-inspection by CCD.
- Clean Room management (class 1K) in critical production floors.



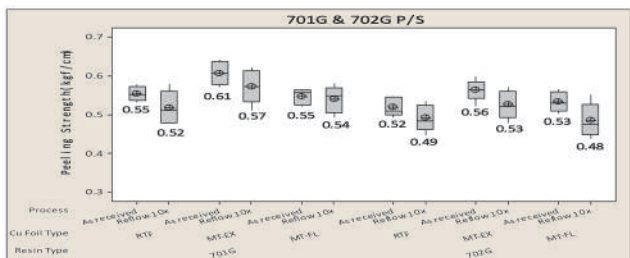
樹脂配方 RESIN MIXTURE

- Improved thermal reliability/Good dimensional stability/Low moisture absorption/Good for MFG.
- Suitable for hot press and vacuum laminator.



拉力值 PEELING STRENGTH

- Both IT-701G & IT-702G have good adhesion with each Cu foil even after 10 times reflow.



雷射加工 LASER DRILLABLE

Laser Process

- Machine : Vela ECO-TL2B
- Laser drilling condition

Mask: 1.5 mm dia.
Energy: 3 µm Cu foil → 11.2-2.3 W
12 µm Cu foil → 9-4 µs
12 µm Cu foil → 11.1-2.3 W
12 µm Cu foil → 9-5 µs

Construction

Ø= 70 µm

- Cu Thk. = 3 or 12
- Surface treated
- RCC = 0.045 mm
- Core 0.2 mm
- Inner copper treated

Result of 3 µm Cu foil

- Top via: 72 µm
- Bottom via: 67 µm
- Taper: 93%
- Overhang: 7.2 µm

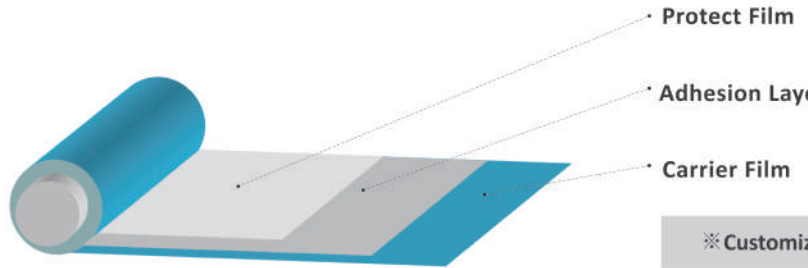
Result of 12 µm Cu foil

- Top via: 73 µm
- Bottom via: 66 µm
- Taper: 90%
- Overhang: 5.9 µm

LIFT-OFF TAPE / FUNCTIONAL PROTECTIVE FILM

Specifications		ILF-1004B	IPF-6001
Application		Lift-off Tape	Protect Film
離型層 Protect film	材質/厚度 (μm) Materials/Thickness (μm)	PET / 50	PET / 50
黏性層 Adhesive Layer		Acrylic / 20	Acrylic / 10
基材 Carrier Film		PET / 100	PI / 12.5
黏著力 Adhesion (gf/25mm)	R.T. 25°C	65 ±25	15 ± 5
	After 200°C, 30min	-	80 ± 20 No glue residue
表面阻抗 Surface Resistance	膠面 (黏性層)	10 ⁹	>10 ¹¹

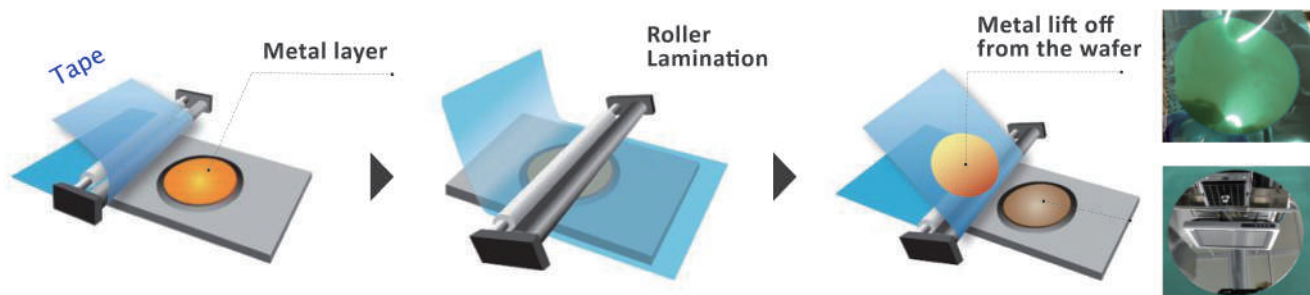
◆ Product structure & Product Specifications

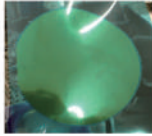



Product Specifications	
Width	180 - 600 mm
Length	200 M

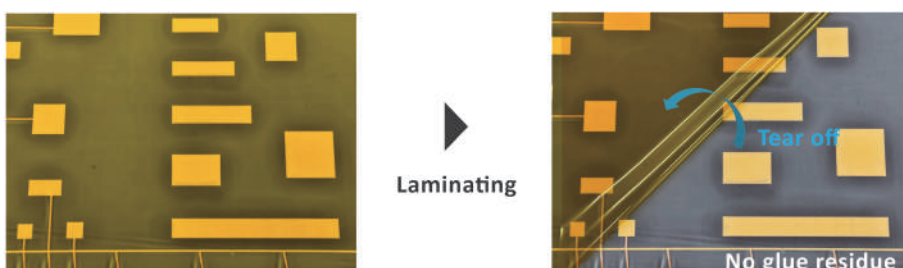
※ Customization of the film type and thickness is available

◆ Lift-off Tape



◆ Protect Film



Lamination Process	
Temperature	200 °C
Time	90 min

Applicable material:
Cu \ Au \ Resin ...etc

FCCL FOR HIGH-SPEED AND HIGH-FREQUENCY



- Smartphone antenna
- display cable

- USB 3.1/3.2
- LTE/WIFI/Bluetooth module

- Optical module

Low Loss FCCL

◆ IF-2LD-B

MPI base D/S and S/S copper clad laminate

- Outstanding performance in dielectric loss

◆ IF-LCD

LCP-base D/S and S/S copper clad laminate

- Low water absorption
- Halogen free

◆ IF-LGD

Fluoro-base double-sided copper clad laminate

Low Loss Coverlay / Bonding Sheet

◆ IF-LC / IF-LC-L / IF-MC (Black)

PI base low loss Coverlay

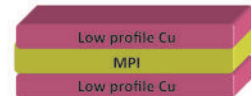
◆ IF-BL

- Low loss bonding sheet

- Outstanding performance in dielectric loss
- Excellent high temperature resistance
- Low water absorption

◆ General Properties

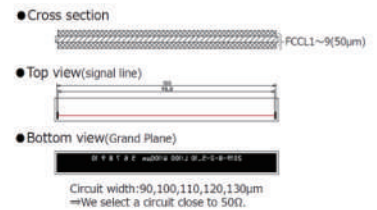
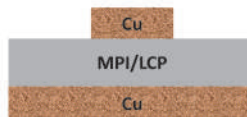
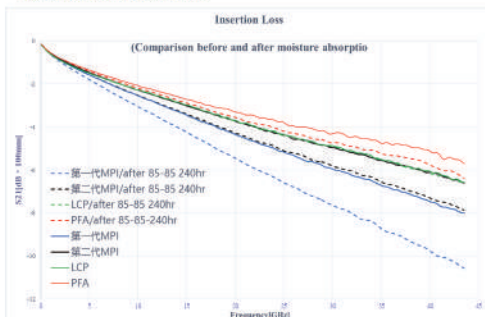
FCCL		MPI		LCP	PFA	Remark	
Test Item	Condition	NO.1	NO.2			Standard	Test Method
Thickness	um	50+12		50+12	50+12	± 10%	/
Solder Resistance	300°C/10S	Pass	Pass	Pass	Pass	300°C/10S	IPC-TM-650 2.4.13
Peel Strength	90°(Kgf/cm)	1.25	1.26	0.9	1.03	≥ 0.5	IPC-TM-650 2.4.9
Water Absorption	Dipping/24h	0.7%	0.4%	0.04%	0.4%	≤ 1.2%	IPC-TM-650 2.6.2
Dk	10GHz	3.1	3.1	3.1	2.8	≤ 3.2	IPC-TM-650 2.5.5*
Df	10GHz	0.006	0.0025	0.002	0.0025	≤ 0.009	IPC-TM-650 2.5.5*
Flame class		V-0	V-0	/	/	UL94	UL94



Coverlay / Bonding sheet		IF-LC	IF-LC-L	IF-MC	IF-BL25	Remark	
Test Item	Condition					Standard	Test Method
Thickness	um	12.5+25	12.5+25	12.5+25	25	± 10%	/
Solder Resistance	300°C/10S	Pass	Pass	Pass	Pass	300°C/10S	IPC-TM-650 2.4.13
Peel Strength	90°(Kgf/cm)	1.21	1.20	1.20	1.36	≥ 0.5	IPC-TM-650 2.4.9
Water Absorption	Dipping/24h	0.4%	0.4%	0.4%	0.4%	≤ 1.2%	IPC-TM-650 2.6.2
Dk	10GHz	2.8	3.1	3.2	2.7	≤ 3.2	IPC-TM-650 2.5.5*
Df	10GHz	0.006	0.0046	0.011	0.0025	≤ 0.009	IPC-TM-650 2.5.5*
Flame Class		VTM-0	VTM-0	VTM-0	VTM-0	UL94	UL94

◆ Transmission Loss

*Test with Syntonic Cavity Method



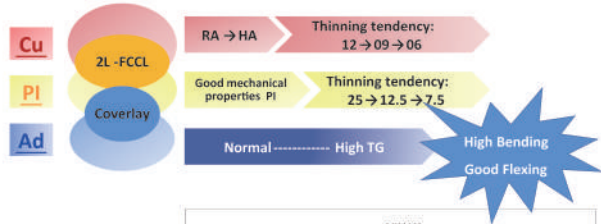
Material:

	Type		Cu	Dielectric
	NO.1	NO.2		
MPI	NO.1	IF-2LD-L5012L*	12	50
	NO.2	IF-2LD-B5012B*	12	50
PFA		IF-LGD251212FF*	12	50
LCP		IF-LCD05012**	12	50

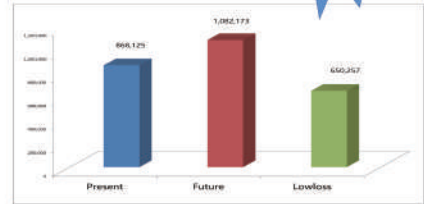
FCCL For Automotive and 3C

◆ IF-2LS/IF-HC series

- Good mechanical properties PI
- HA copper
- High Tg Coverlay (Tg ≥ 110°C)
- PI is inadhesive in layered structure
- ★ Application : Folding Phone, AR/VR, and CCM

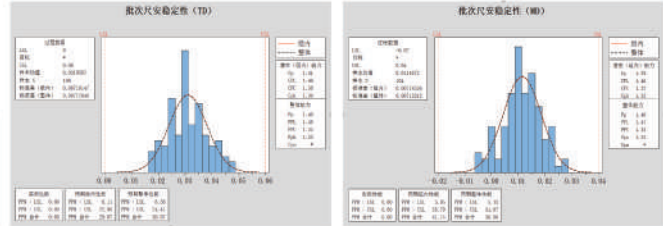
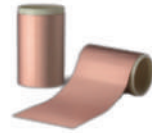
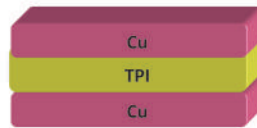


Project	FCCL (HA)	Coverlay	Times
Present	Good mechanical properties PI	IF-2LS1312VY-C 12.5 Good mechanical properties PI+High Tg AD	IF-HC1315NMG 868,125
Future	Good mechanical properties PI	IF-2LS1309VY 7.5 Good mechanical properties PI+High Tg AD	IF-HC0815GMG 1,082,173
Low loss	MPI	IF - 2LS - M1312MU1 7.5 low loss PI+low loss AD IF	IF-LC0815GUN 650,257



◆ IF-2LD-I series

- Dimensional stability (D.S ≤ 2%)
- Excellent flexibility
- ★ Application : OLED/Auto-LCM



◆ No-dendrite Coverlay series

- Normal : IF-FC , DC50V, 500h , No-dendrite , ≥108Ω
- Consumers : IF-FC (-K) , DC50V, 1000h , No-dendrite , ≥108Ω
- Automobile : IF-FC(NSG) , DC100V, 1500h , No-dendrite , ≥108Ω
- ★ Application : Fine Pitch/Multi-layer FPC/High Reliability FPC



Type	50V/100V 85°C / 85%RH L/S = 50μm/ 50μm	
	Resistance 108Ω	PI/AD=12.5/15 Appearance
IF-FC1315NHF (50V 500h)		
IF-FC1315NHF (50V 500h)		
IF-FC1315NHF (50V 500h)		

◆ IF-2LD Thick TPI series

- PI : 2mil/3mil/4mil
- High dielectric strength and tear strength
- ★ Application : Rigid-flex (Radar, Industry, medical, aerospace)

